

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Specification:

On Page 5, the second complete paragraph (Lines 14-20) is modified as follows:

5 The semiconductor wafer is placed on a test system and each integrated circuit chip is tested ~~220~~215 for functionality. The functioning chips are denoted as functional die. The semiconductor wafer is then diced ~~220~~ and the functional die are separated for further assembly ~~225~~ in a first level or module package. The selection or omission of connections between the functional integrated circuit die
10 and the first level package is a custom design particular to each combination of desired functions.